

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00987	2.0	0.164
	Lead alloy	Silver (Ag)	7440-22-4	0.01234	2.5	0.205
	Lead alloy	Lead (Pb)	7439-92-1	0.4714	95.5	7.831
		Subtotal		0.49361	100	8.2
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01295	0.03	0.2151
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01295	0.03	0.2151
	Copper alloy	Iron (Fe)	7439-89-6	0.04316	0.1	0.717
	Copper alloy	Copper (Cu)	7440-50-8	43.09169	99.84	715.8528
		Subtotal		43.16075	100	717
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.19115	4.0	36.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	8.2168	15.0	136.5
	Filler	Silica fused	60676-86-0	40.53619	74.0	673.4
	Flame retardant	Metal hydroxide		3.8345	7.0	63.7
		Subtotal		54.77864	100	910
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.50491	100.0	25
		Subtotal		1.50491	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04524	100.0	0.75148
		Subtotal		0.04524	100	0.75148
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01685	100.0	0.28
		Subtotal		0.01685	100	0.28
		Total		100	100	1661.23148

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